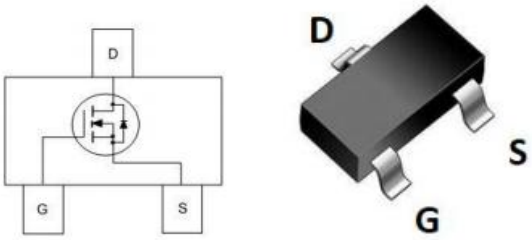
SOT-23 100V N Channel Enhancement 沟道增强型
MOS Field Effect Transistor 场效应管



■Absolute Maximum Ratings 最大额定值

Characteristic 特性参数	Symbol 符号	Rat 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	BV_{DSS}	100	V
Gate- Source Voltage 栅极-源极电压	V_{GS}	±20	V
Drain Current (continuous)漏极电流-连续	I_D（at T_A = 25°C）	3.3	A
Drain Current (pulsed)漏极电流-脉冲	I_{DM}	12	A
Total Device Dissipation 总耗散功率	P_D(at T_A = 25°C)	1400	mW
Thermal Resistance Junction-Ambient 热阻	$R_{\Theta JA}$	89	℃/W
Junction/Storage Temperature 结温/储存温度	T_J,T_{stg}	-55~150	℃

■Device Marking 产品字标

FS3N10M=3N10

■Electrical Characteristics 电特性

(T_A=25℃ unless otherwise noted 如无特殊说明，温度为 25℃)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压(I_D =250uA,V_{GS}=0V)	BV_{DSS}	100	—	—	V
Gate Threshold Voltage 栅极开启电压(I_D =250uA,V_{GS}= V_{DS})	$V_{GS(th)}$	1	1.65	2.5	V
Zero Gate Voltage Drain Current 零栅压漏极电流(V_{GS}=0V, V_{DS}= 100V)	I_{DSS}	—	—	1	uA
Gate Body Leakage 栅极漏电流(V_{GS}=±20V, V_{DS}=0V)	I_{GSS}	—	—	±100	nA
Static Drain-Source On-State Resistance 静态漏源导通电阻(I_D=3A,V_{GS}=10V) (I_D=1A,V_{GS}=4.5V)	$R_{DS(ON)}$	—	90 120	100 130	mΩ
Diode Forward Voltage Drop 内附二极管正向压降(I_{SD}=3A,V_{GS}=0V)	V_{SD}	—	—	1.3	V
Input Capacitance 输入电容 (V_{GS}=0V, V_{DS}=50V,f=1MHz)	C_{ISS}	—	210	—	pF
Common Source Output Capacitance 共源输出电容(V_{GS}=0V, V_{DS}=50V,f=1MHz)	C_{OSS}	—	30	—	pF
Reverse Transfer Capacitance 反馈电容(V_{GS}=0V, V_{DS}=50V,f=1MHz)	C_{RSS}	—	2	—	pF
Total Gate Charge 栅极电荷密度 (V_{DS}=50V, I_D=3A, V_{GS}=10V)	Q_g	—	4	—	nC
Gate Source Charge 栅源电荷密度 (V_{DS}=50V, I_D=3A, V_{GS}=10V)	Q_{gs}	—	2	—	nC
Gate Drain Charge 栅漏电荷密度 (V_{DS}=50V, I_D=3A, V_{GS}=10V)	Q_{gd}	—	1	—	nC
Turn-ON Delay Time 开启延迟时间 (V_{DS}=50V I_D=1.5A, R_{GEN}=1Ω,V_{GS}=10V)	$t_{d(on)}$	—	15	—	ns
Turn-ON Rise Time 开启上升时间 (V_{DS}=50V I_D=1.5A, R_{GEN}=1Ω,V_{GS}=10V)	t_r	—	5	—	ns
Turn-OFF Delay Time 关断延迟时间 (V_{DS}=50V I_D=1.5A, R_{GEN}=1Ω,V_{GS}=10V)	$t_{d(off)}$	—	22	—	ns
Turn-OFF Fall Time 关断下降时间 (V_{DS}=50V I_D=1.5A, R_{GEN}=1Ω,V_{GS}=10V)	t_f	—	3	—	ns

■Typical Characteristic Curve 典型特性曲线

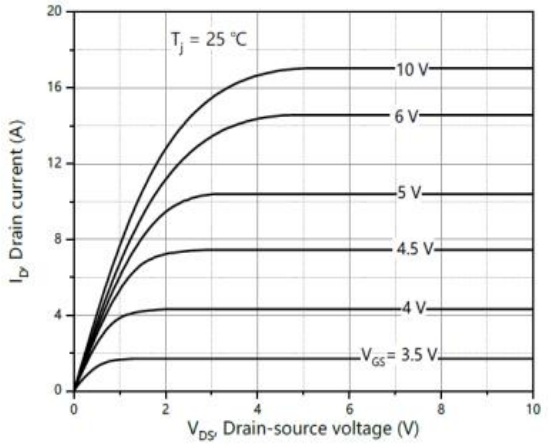


Figure 1: Output Characteristics

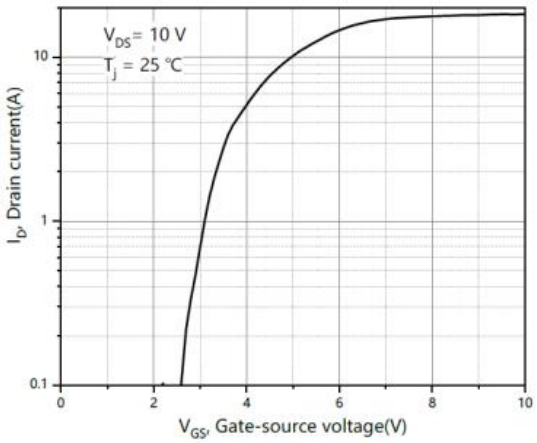


Figure 2: Transfer Characteristics

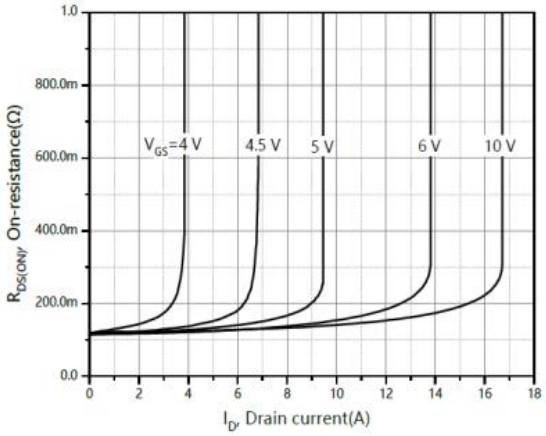


Figure 3: On-Resistance vs. Drain Current

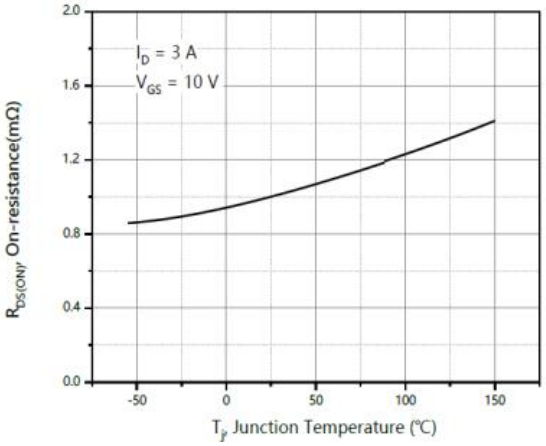


Figure 4: On-Resistance vs. Temperature

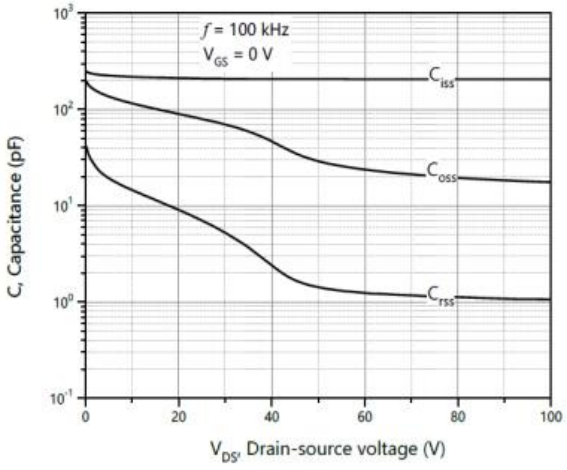


Figure 5: Capacitance Characteristics

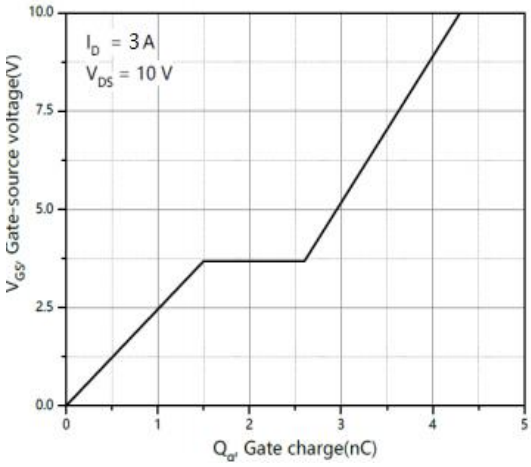


Figure 6: Gate-Charge Characteristics

■Typical Characteristic Curve 典型特性曲线

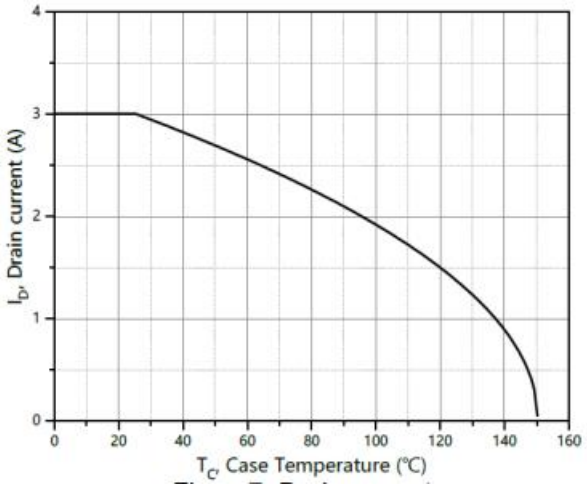


Figure 7: Drain Current vs. Temperature

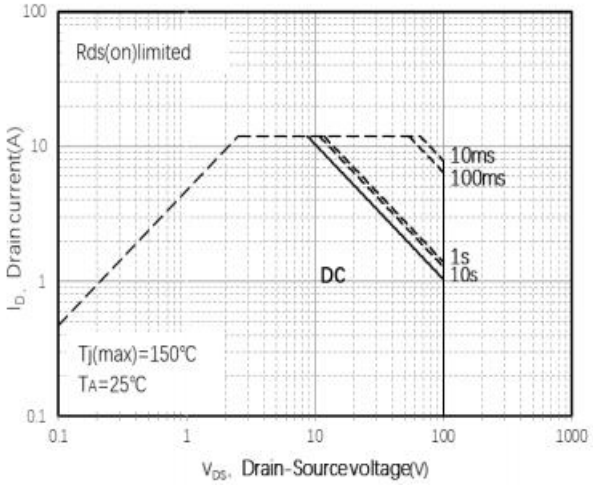


Figure 8: Safe Operating Area

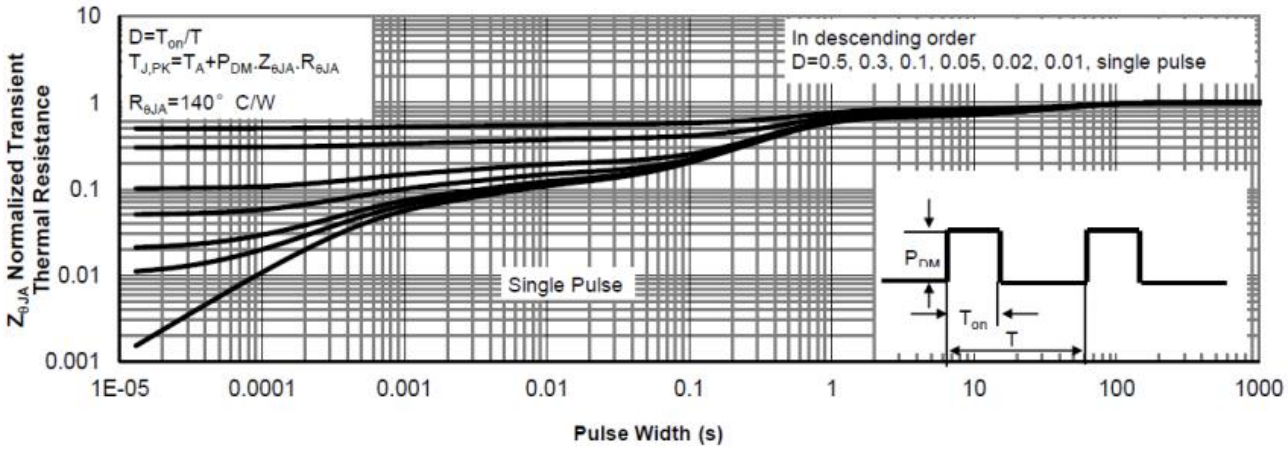
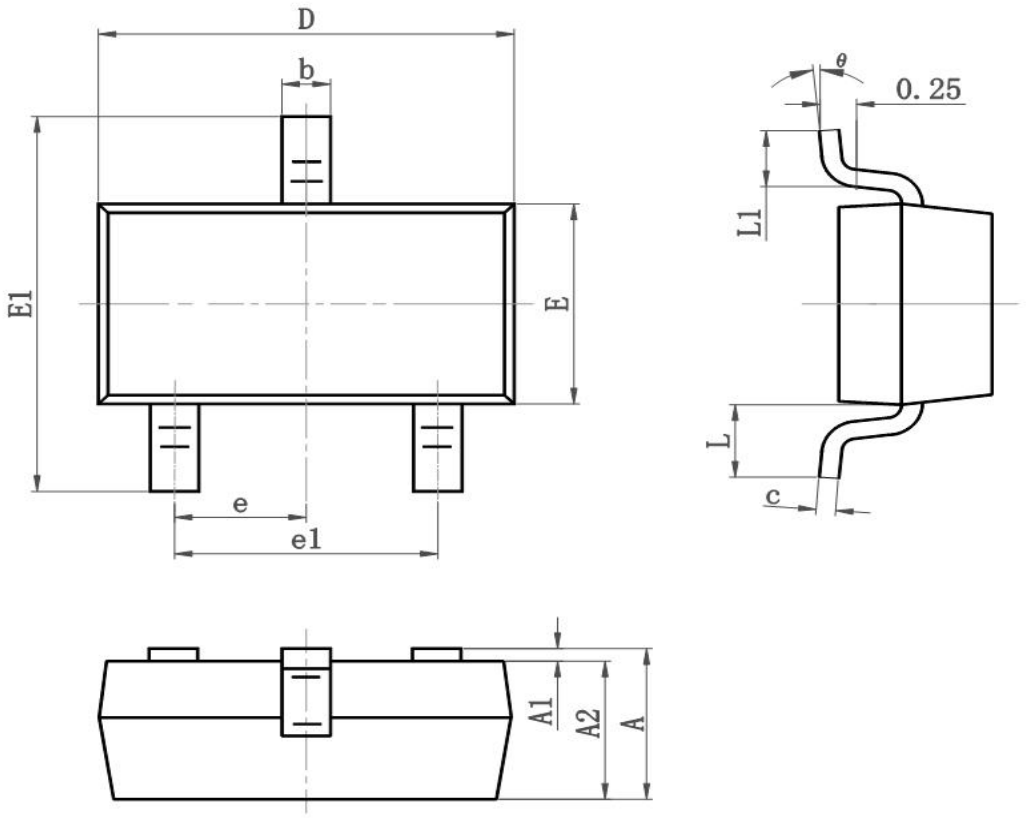


Figure 9: Transient Thermal Response Curve

■Dimension 外形封装尺寸



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.050	0.055
E1	2.250	2.550	0.089	0.100
e	0.900	1.00	0.035	0.039
e1	1.800	2.000	0.071	0.079
L	0.500	0.600	0.020	0.024
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°